FAIRCHILD SEMICONDUCTOR®

October 2006

FAN7382
Half-Bridge Gate-Driver IC

Features

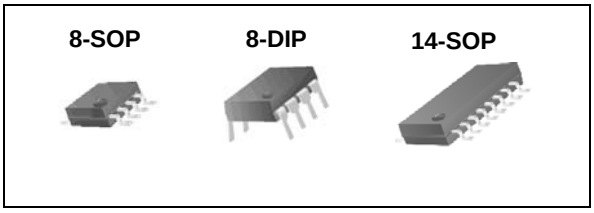
- Floating Channels Designed for Bootstrap Operation to +600V
- Typically 350mA/650mA Sourcing/Sinking Current Driving Capability for Both Channels
- Common-Mode dv/dt Noise Canceling Circuit
- Extended Allowable Negative V_S Swing to -9V for Signal Propagation at V_{CC}=V_{BS}=15V
- V_{CC} & V_{BS} Supply Range from 10V to 20V
- UVLO Functions for Both Channels
- TTL Compatible Input Logic Threshold Levels
- Matched Propagation Delay Below 50nsec
- Output In-phase with Input

Applications

- PDP Scan Driver
- Fluorescent Lamp Ballast
- SMPS
- Motor Driver

Description

The FAN7382, a monolithic half-bridge gate-driver IC, can drive MOSFETs and IGBTs that operate up to +600V. Fairchild's high-voltage process and common-mode noise canceling technique provides stable operation of the high-side driver under high-dv/dt noise circumstances. An advanced level-shift circuit allows high-side gate driver operation up to V_S=-9.8V (typical) for V_{BS}=15V. The input logic level is compatible with standard TTL-series logic gates. UVLO circuits for both channels prevent malfunction when V_{CC} or V_{BS} is lower than the specified threshold voltage. Output drivers typically source/sink 350mA/650mA, respectively, which is suitable for fluorescent lamp ballasts, PDP scan drivers, motor controls, etc.



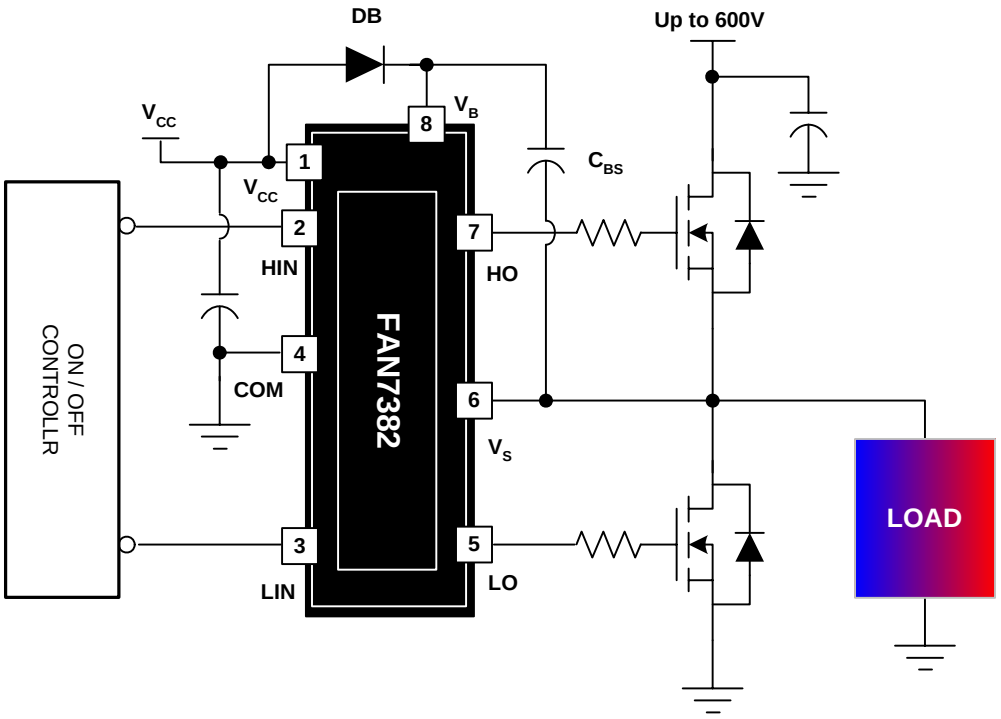
Ordering Information

Part Number	Package	Pb-Free	Operating Temperature Range	Packing Method
FAN7382N	8-DIP	Yes	-40°C ~ 125°C	Tube
FAN7382M(1)	8-SOP			Tube
FAN7382MX(1)				Tape & Reel
FAN7382M1	14-SOP			Tube
FAN7382M1X				Tape & Reel

Note:

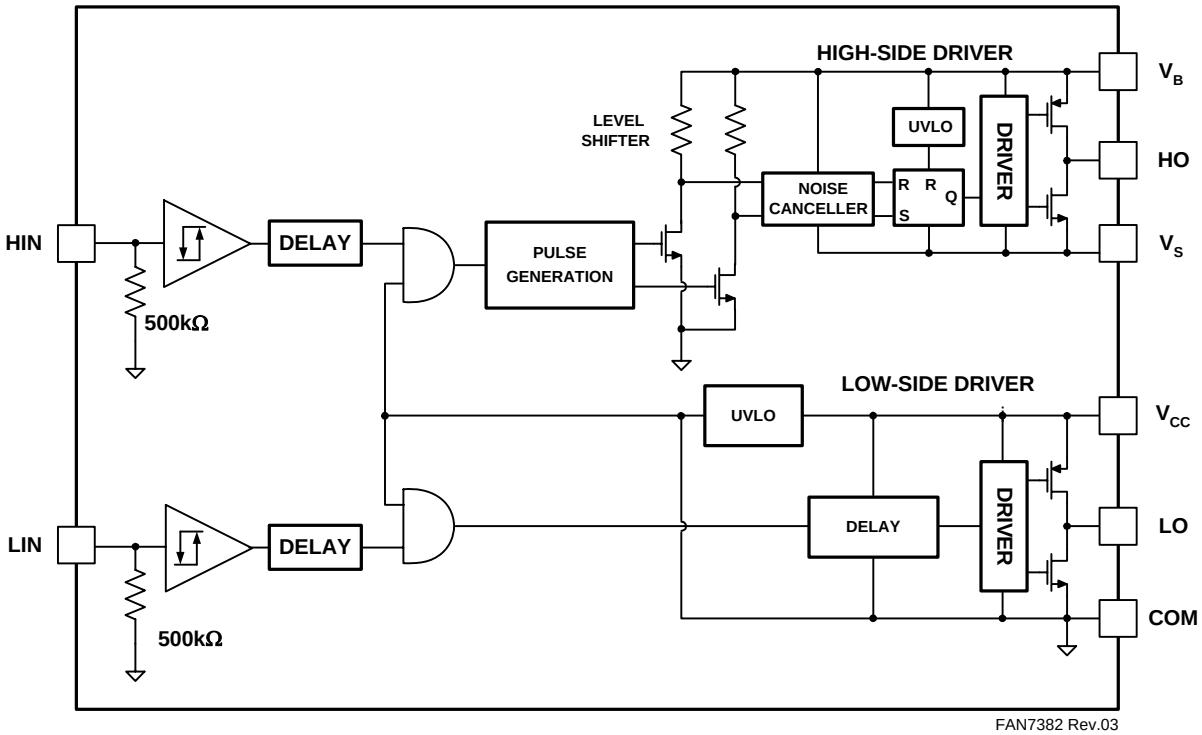
1. These devices passed wave soldering test by JESD22A-111.

Typical Application Circuit



FAN7382 Rev.04

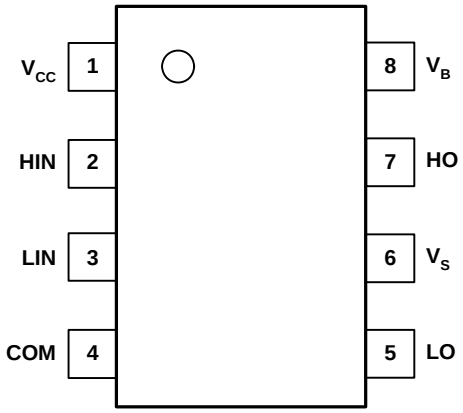
Internal Block Diagram



FAN7382 Rev.03

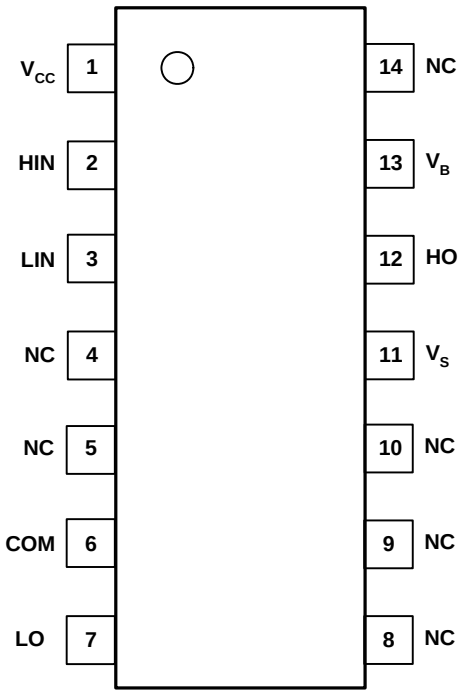
Pin Assignments

FAN7382N
FAN7382M



FAN7382 Rev.04

FAN7382M1



FAN7382 Rev.00

Pin Definitions

Name	Description
V_{CC}	Low-Side Supply Voltage
HIN	Logic Input for High-Side Gate Driver Output
LIN	Logic Input for Low-Side Gate Driver Output
COM	Logic Ground and Low-Side Driver Return
LO	Low-Side Driver Output
V_S	High-Voltage Floating Supply Return
HO	High-Side Driver Output
V_B	High-Side Floating Supply

Absolute Maximum Ratings

The “Absolute Maximum Ratings” are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings.

Symbol	Characteristics	Min.	Max.	Unit
V_S	High-side offset voltage	V_B-25	V_B+0.3	V
V_B	High-side floating supply voltage	-0.3	625	
V_{HO}	High-side floating output voltage HO	V_S-0.3	V_B+0.3	
V_{CC}	Low-side and logic fixed supply voltage	-0.3	25	
V_{LO}	Low-side output voltage LO	-0.3	V_{CC}+0.3	
V_{IN}	Logic input voltage (HIN, LIN)	-0.3	V_{CC}+0.3	
COM	Logic ground	V_{CC}-25	V_{CC}+0.3	
dV_S/dt	Allowable offset voltage slew rate		50	V/nsec
P_D	Power dissipation	8-SOP	0.625	W
		14-SOP	1.0	
		8-DIP	1.2	
θ_{JA}	Thermal resistance, junction-to-ambient	8-SOP	200	°C/W
		14-SOP	110	
		8-DIP	100	
T_J	Junction temperature		150	°C
T_{STG}	Storage temperature		150	°C

Electrical Characteristics

V_{BIAS} (V_{CC}, V_{BS})=15.0V, T_A = 25°C, unless otherwise specified. The V_{IN}, V_{TH}, and I_{IN} parameters are referenced to COM. The V_O and I_O parameters are referenced to COM and V_S is applicable to HO and LO.

Symbol	Characteristics	Test Condition	Min.	Typ.	Max.	Unit
V_{CCUV+} V_{BSUV+}	V_{CC} and V_{BS} supply under-voltage positive going threshold		8.2	9.2	10.0	V
V_{CCUV-} V_{BSUV-}	V_{CC} and V_{BS} supply under-voltage negative going threshold		7.6	8.7	9.6	
V_{CCUVH} V_{BSUVH}	V_{CC} supply under-voltage lockout hysteresis			0.6		
I_{LK}	Offset supply leakage current	V_B=V_S=600V			50	µA
I_{QBS}	Quiescent V_{BS} supply current	V_{IN}=0V or 5V		45	120	
I_{QCC}	Quiescent V_{CC} supply current	V_{IN}=0V or 5V		70	180	
I_{PBS}	Operating V_{BS} supply current	f_{IN}=20kHz,rms value			600	µA
I_{PCC}	Operating V_{CC} supply current	f_{IN}=20kHz,rms value			600	
V_{IH}	Logic "1" input voltage		2.9			V
V_{IL}	Logic "0" input voltage				0.8	
V_{OH}	High-level output voltage, V_{BIAS}-V_O	I_O=20mA			1.0	
V_{OL}	Low-level output voltage, V_O				0.6	
I_{IN+}	Logic "1" input bias current	V_{IN}=5V		10	20	µA
I_{IN-}	Logic "0" input bias current	V_{IN}=0V		1.0	2.0	
I_{O+}	Output high short-circuit pulsed current	V_O=0V,V_{IN}=5V with PW<10µs	250	350		mA
I_{O-}	Output low short-circuit pulsed current	V_O=15V=V_B,V_{IN}=0V with PW<10µs	500	650		
V_S	Allowable negative V_S pin voltage for HIN signal propagation to HO			-9.8	-7.0	V

Dynamic Electrical Characteristics

V_{BIAS} (V_{CC}, V_{BS})=15.0V, V_S=COM, C_L=1000pF and, T_A = 25°C, unless otherwise specified.

Symbol	Characteristics	Test Condition	Min.	Typ.	Max.	Unit
t_{on}	Turn-on propagation delay	V_S=0V	100	170	300	nsec
t_{off}	Turn-off propagation delay	V_S=0V or 600V	100	200	300	
t_r	Turn-on rise time		20	60	140	
t_f	Turn-off fall time			30	80	
MT	Delay matching, HS & LS turn-on/off				50	

Typical Characteristics

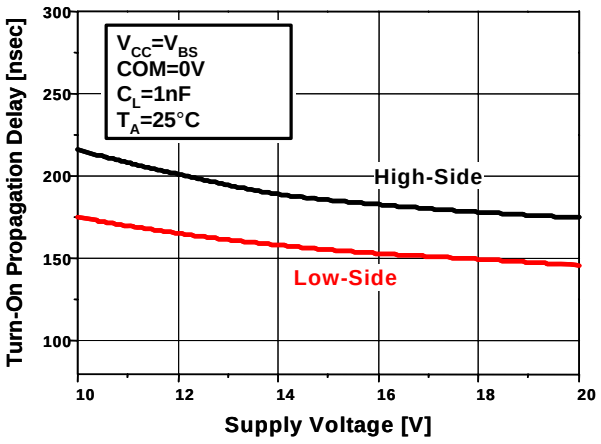


Figure 1. Turn-On Propagation Delay vs. Supply Voltage

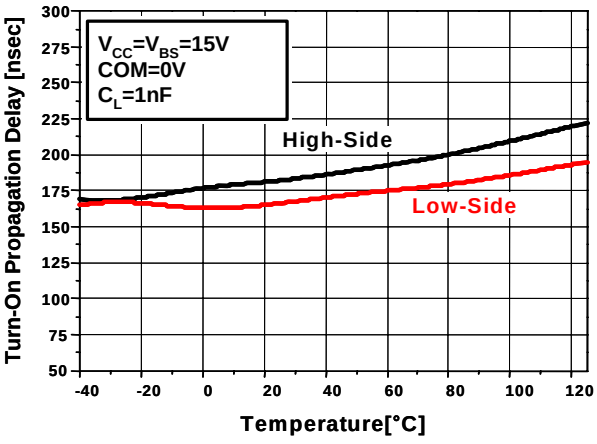


Figure 2. Turn-On Propagation Delay vs. Temp.

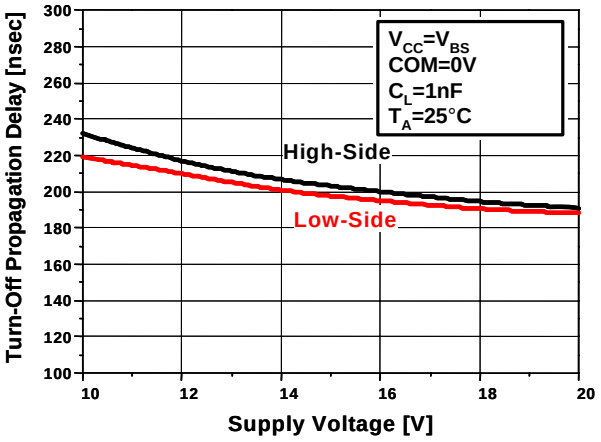


Figure 3. Turn-Off Propagation Delay vs. Supply Voltage

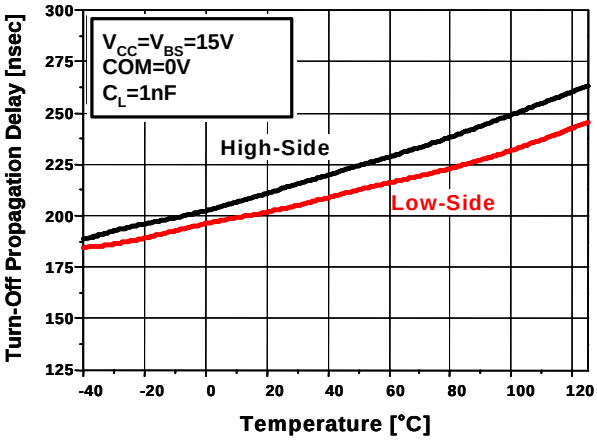


Figure 4. Turn-Off Propagation Delay vs. Temp.

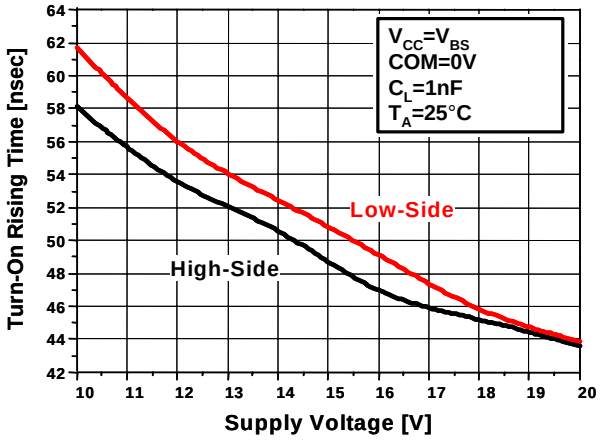


Figure 5. Turn-On Rising Time vs. Supply Voltage

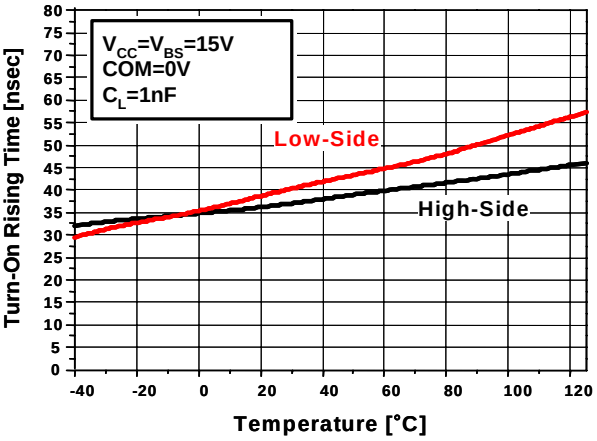


Figure 6. Turn-On Rising Time vs. Temp.

Typical Characteristics (Continued)

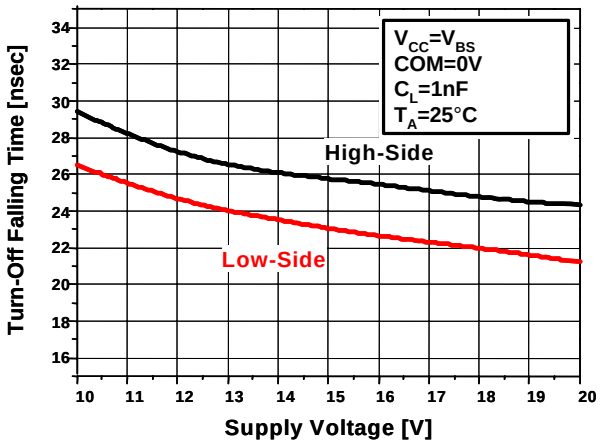


Figure 7. Turn-Off Falling Time vs. Supply Voltage

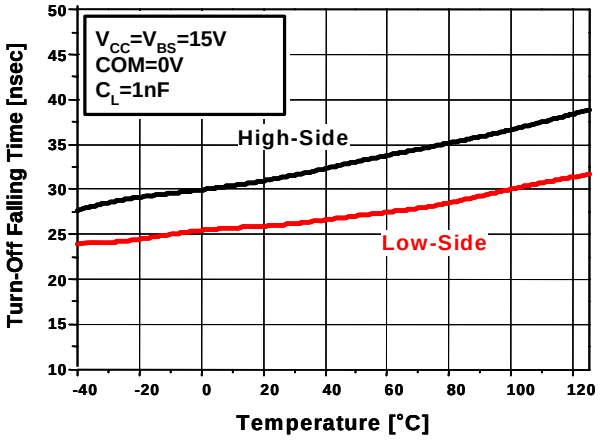


Figure 8. Turn-Off Falling Time vs. Temp.

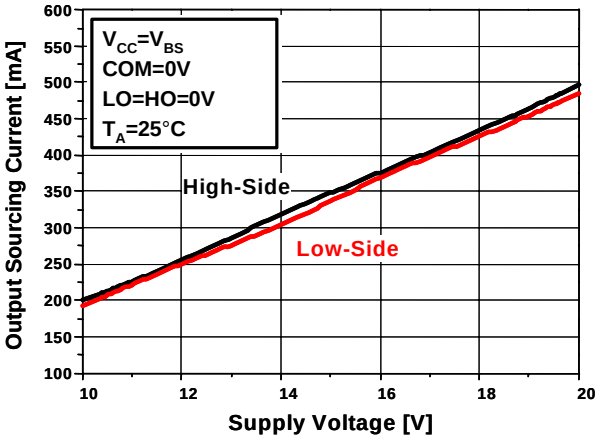


Figure 9. Output Sourcing Current vs. Supply Voltage

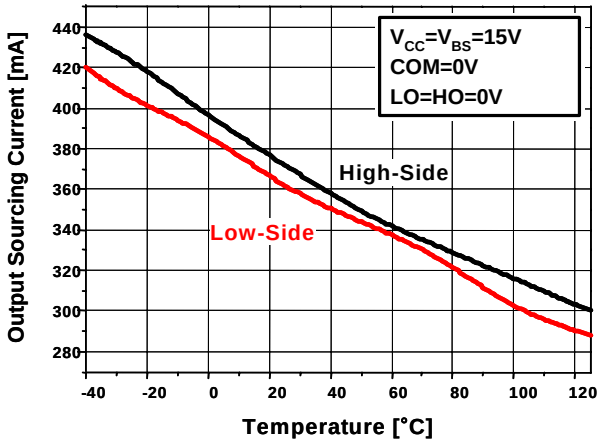


Figure 10. Output Sourcing Current vs. Temp.

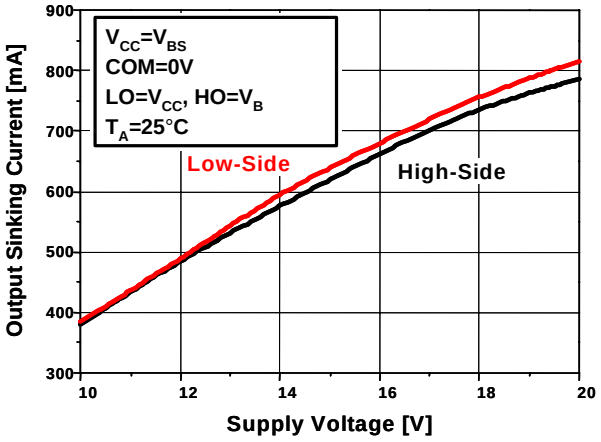


Figure 11. Output Sinking Current vs. Supply Voltage

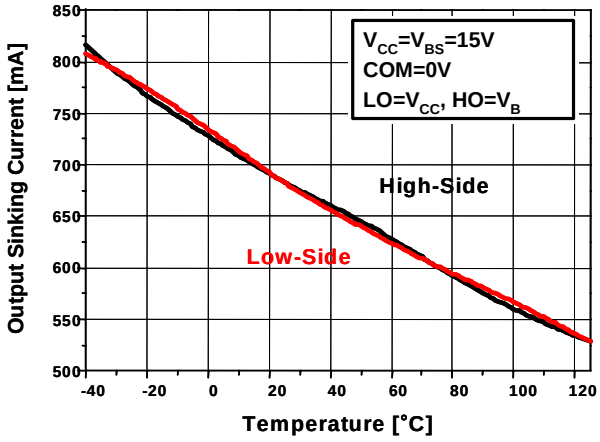


Figure 12. Output Sinking Current vs. Temp.

Typical Characteristics (Continued)

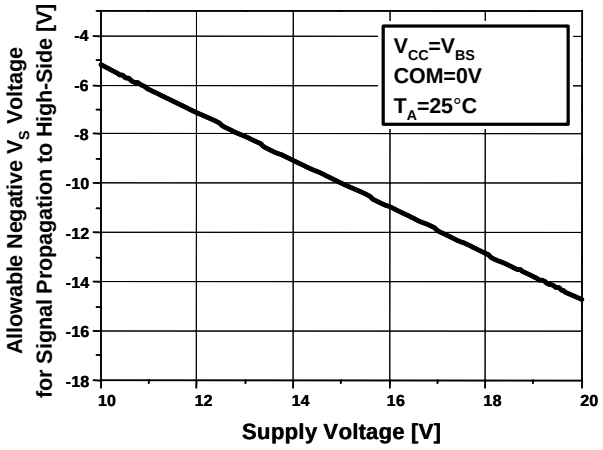


Figure 13. Allowable Negative V_S Voltage for Signal Propagation to High Side vs. Supply Voltage

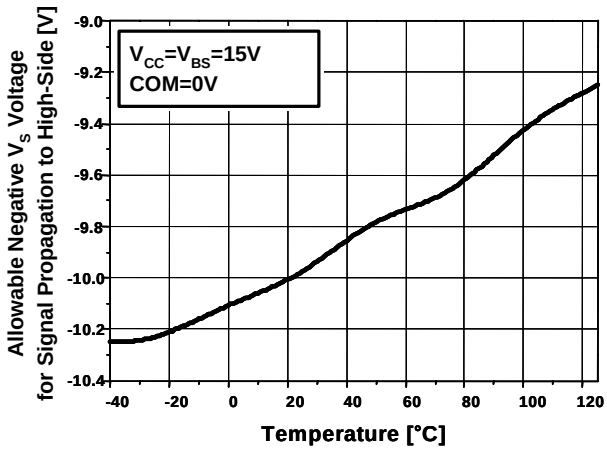


Figure 14. Allowable Negative V_S Voltage for Signal Propagation to High Side vs. Temp.

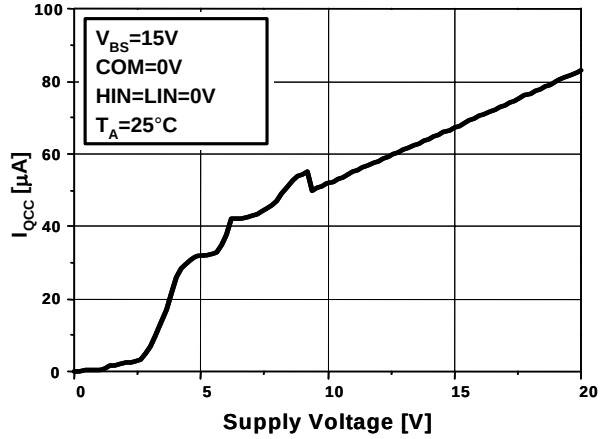


Figure 15. I_{QCC} vs. Supply Voltage

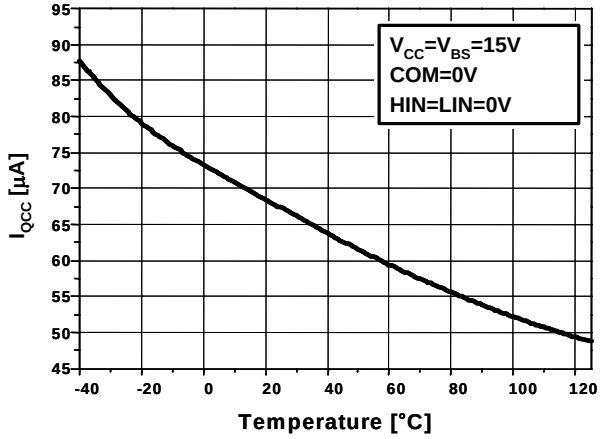


Figure 16. I_{QCC} vs. Temp.

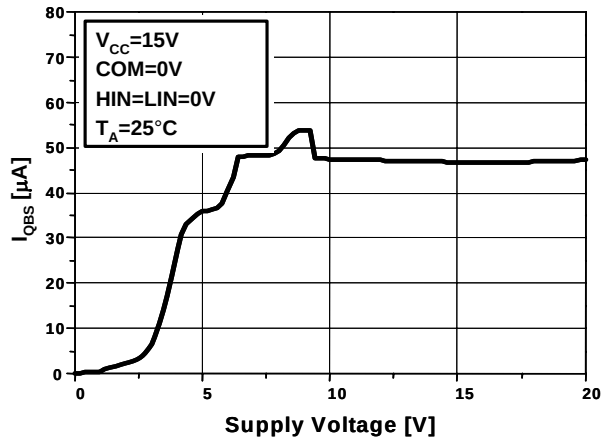


Figure 17. I_{QBS} vs. Supply Voltage

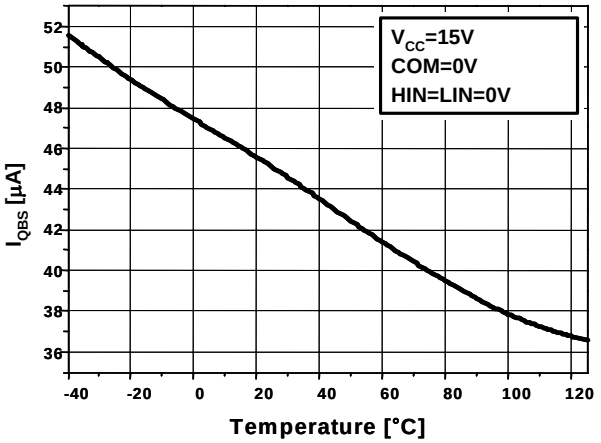


Figure 18. I_{QBS} vs. Temp.

Typical Characteristics (Continued)

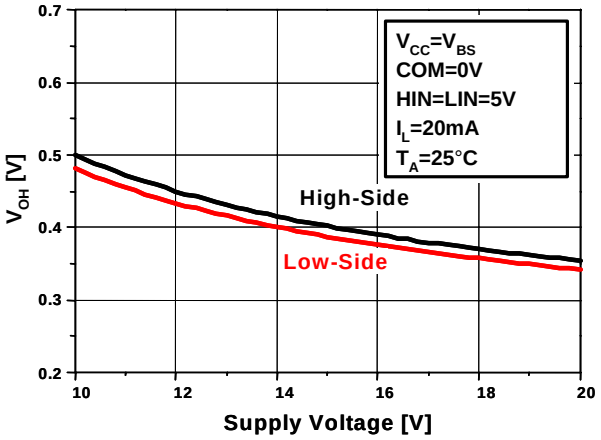


Figure 19. High-Level Output Voltage vs. Supply Voltage

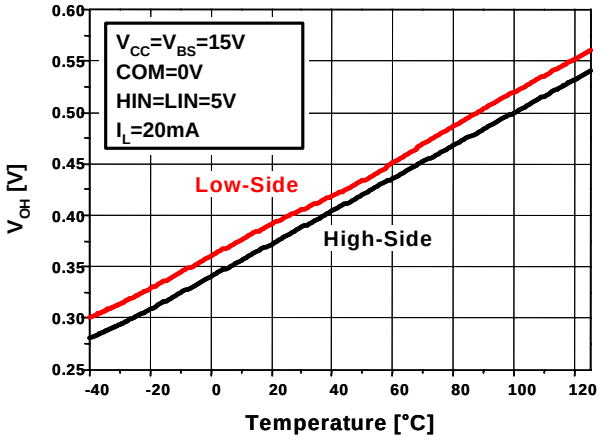


Figure 20. High-Level Output Voltage vs. Temp.

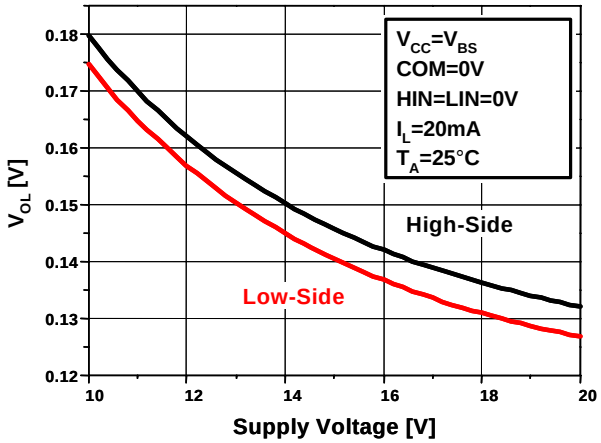


Figure 21. Low-Level Output Voltage vs. Supply Voltage

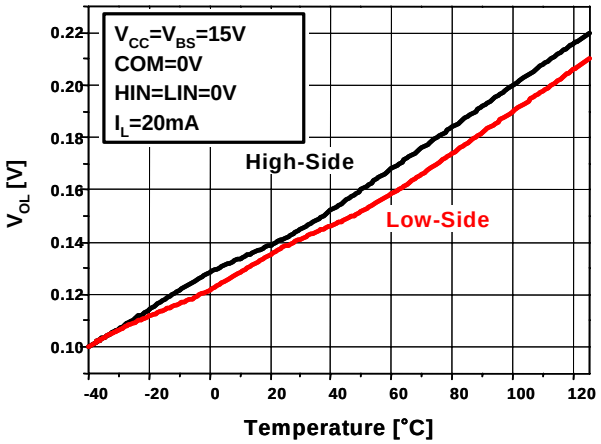


Figure 22. Low-Level Output Voltage vs. Temp.

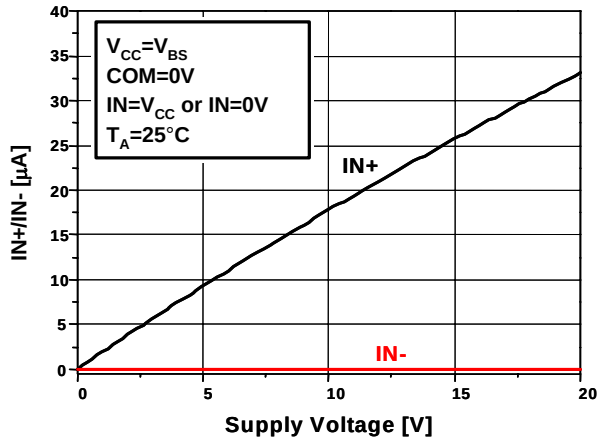


Figure 23. Input Bias Current vs. Supply Voltage

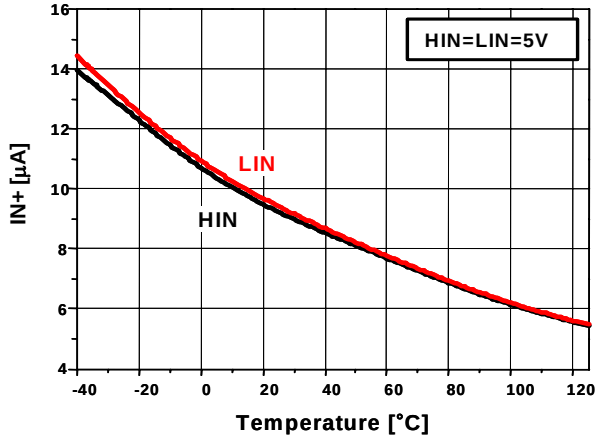


Figure 24. Input Bias Current vs. Temp.

Typical Characteristics (Continued)

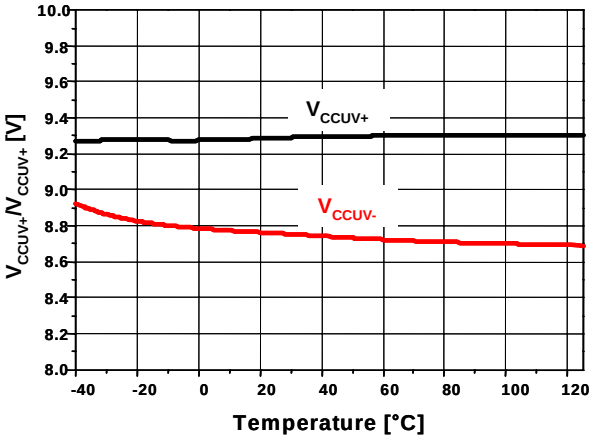


Figure 25. V_{CC} UVLO Threshold Voltage vs. Temp.

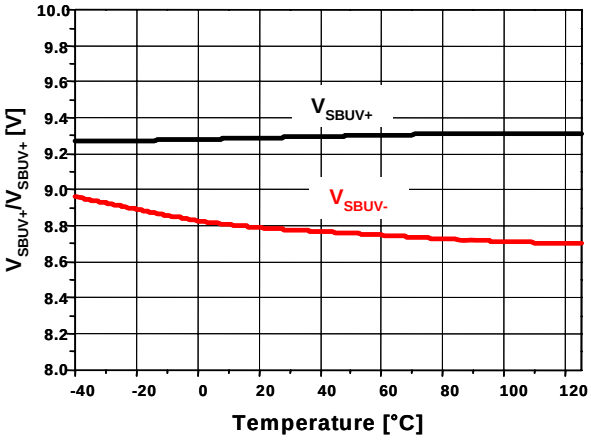


Figure 26. V_{BS} UVLO Threshold Voltage vs. Temp.

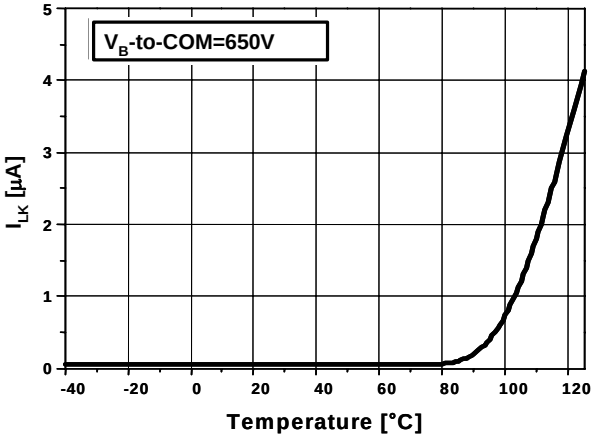


Figure 27. V_B to COM Leakage Current vs. Temp.

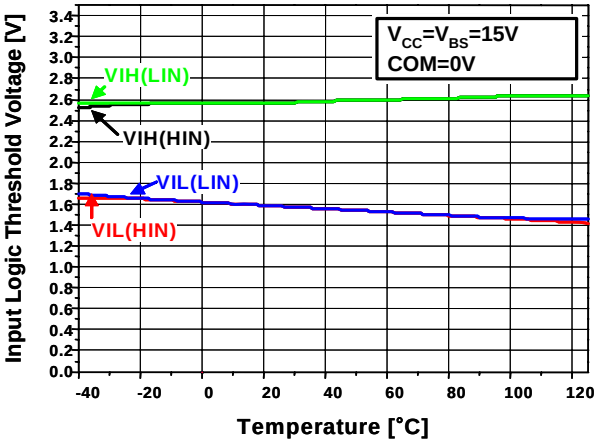


Figure 28. Input Logic Threshold Voltage vs. Temp.

Typical Characteristics (Continued)

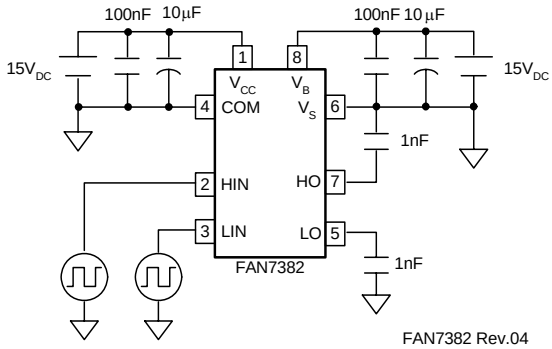


Figure 29. Switching Time Test Circuit

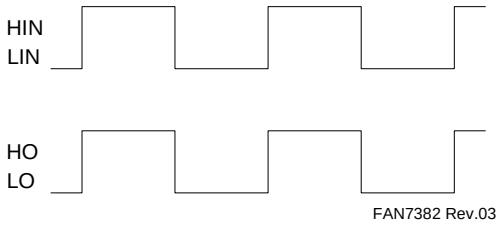


Figure 30. Input / Output Timing Diagram

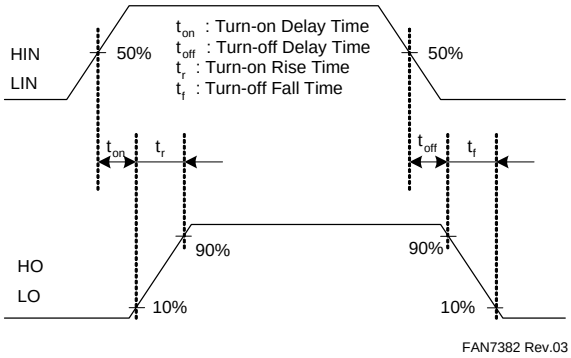


Figure 31. Switching Time Waveform Definition

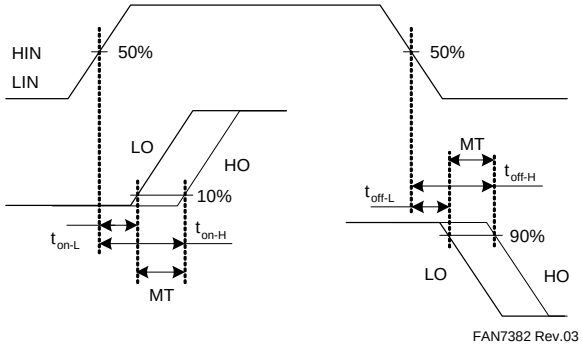


Figure 32. Delay Matching Waveform Definition

Mechanical Dimensions

8-SOP

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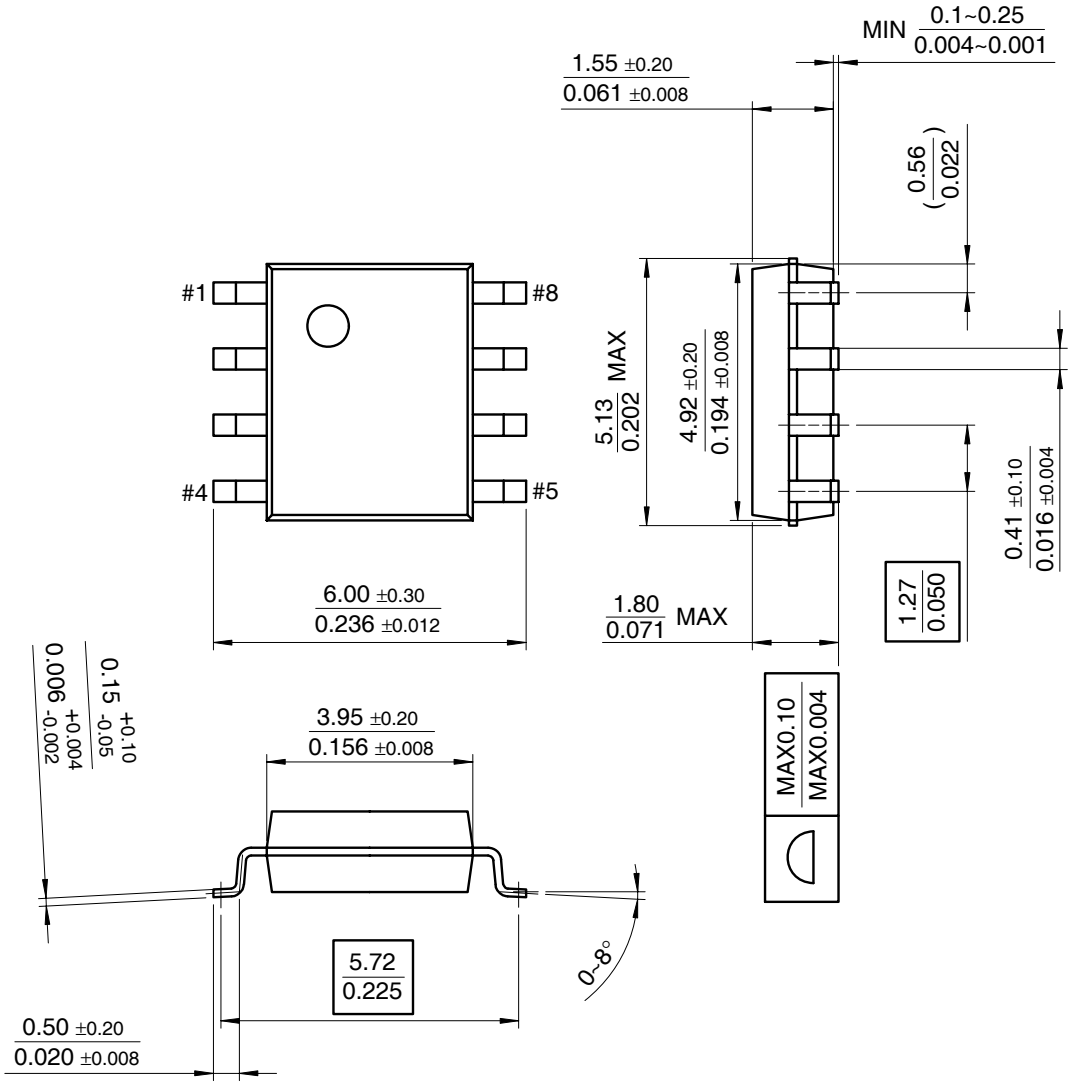

September 2001, Rev B1
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Mechanical Dimensions (Continued)

8-DIP

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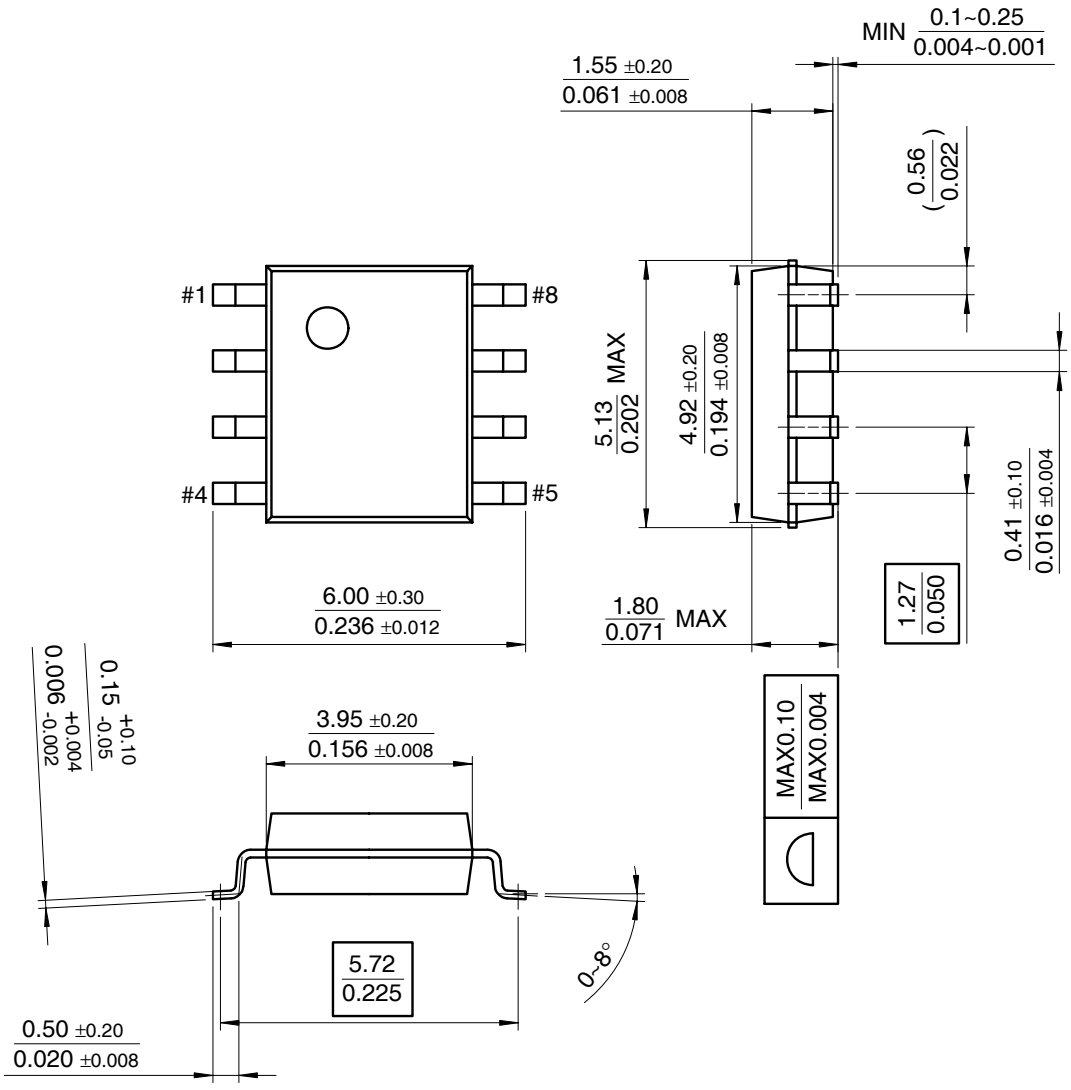

September 2001, Rev B1
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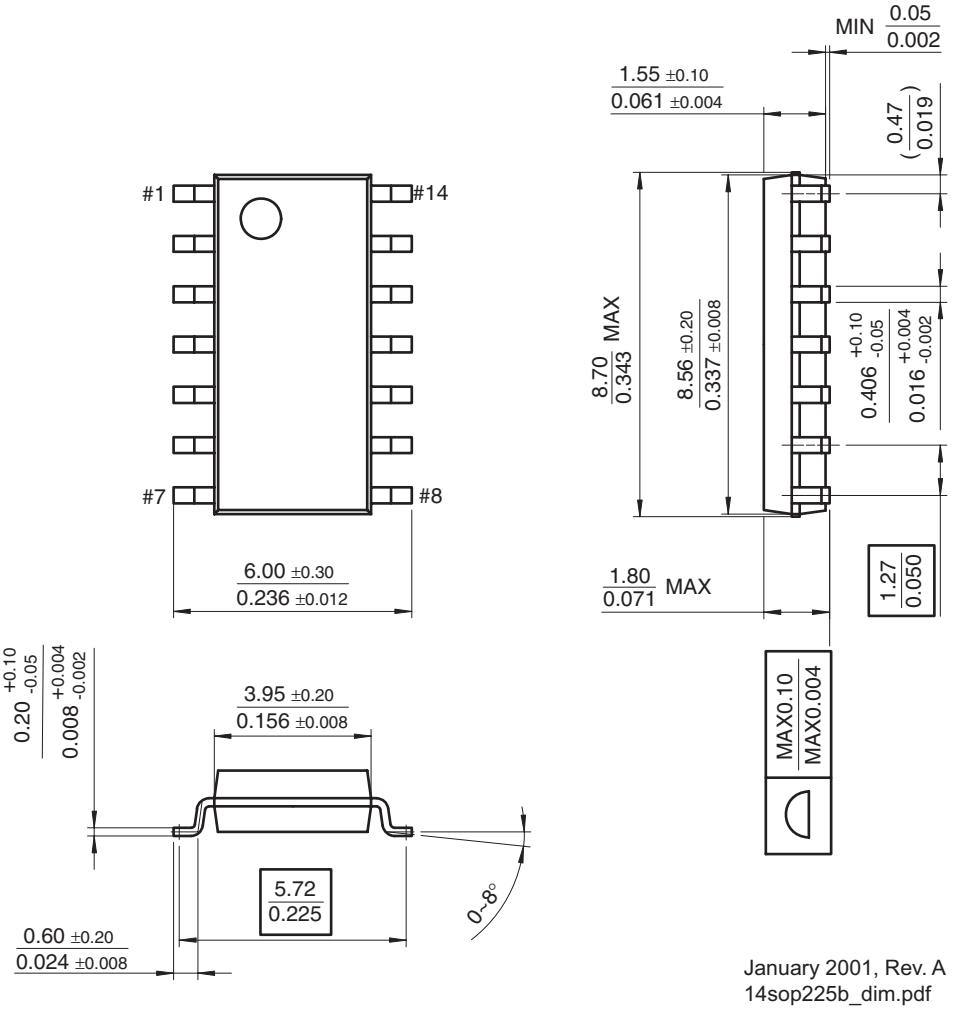
Mechanical Dimensions (Continued)

14-SOP

Dimensions are in millimeters (inches) unless otherwise noted.



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Build it Now™	I^2C™	PACMAN™	SPM™	TinyPower™
CoolFET™	*i-Lo*™	POP™	Stealth™	TinyPWM™
CROSSVOLT™	ImpliedDisconnect™	Power247™	SuperFET™	TruTranslation™
DOME™	IntelliMAX™	PowerEdge™	SuperSOT™-3	UHC™
EcoSPARK™	ISOPLANAR™	PowerSaver™	SuperSOT™-6	UltraFET®
E^2CMOS™	LittleFET™	PowerTrench®	SuperSOT™-8	UniFET™
EnSigna™	MICROCOUPLER™	QFET®	SyncFET™	VCX™
FACT™	MicroFET™	QS™	TCM™	Wire™
FACT Quiet Series™	MicroPak™	QT Optoelectronics™	TinyBoost™	
FAST®	MICROWIRE™	Quiet Series™		
FASTr™	MSX™	RapidConfigure™	Across the board. Around the world.™	
FPS™	MSXPro™	RapidConnect™	Programmable Active Droop™	
FRFET™	OCX™	ScalarPump™	The Power Franchise®	

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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